

Schottky Barrier Rectifier



Features:

- For Surface Mounted Applications
- Low Profile Package
- Built-In Strain Relief
- Metal Silicon Junction, Majority Carrier Conduction
- High Surge Capability
- Low Power Loss, High Efficiency
- For Use in Low Voltage High Frequency Inverters, Free Wheeling and Polarity Protection Applications
- Guardring for Over Voltage Protection
- High Temperature Soldering Guaranteed: 250°C/10 Seconds at Terminals

Mechanical Data

- Case: JEDEC DO-214AC, Molded Plastic over Passivated Chip
- Terminals: Solder Plated, Solderable per MIL-STD-750, Method 2026
- Polarity: Colour Band Denotes Cathode End
- Weight: 0.002oz, 0.064g

Maximum Ratings and Thermal Characteristics

Ratings at 25°C ambient temperature unless otherwise specified

Characteristic		B340A-13-F	B360A-13-F	Units
Maximum repetitive peak reverse voltage	V_{RRM}	40	60	V
Maximum RMS voltage	V_{RWS}	28	42	V
Maximum DC blocking voltage	V_{DC}	40	60	V
Maximum average forward rectified current at T_L . See Fig. 1. (Note 2)	$I_{F(AV)}$	3		A
Peak forward surge current 8.3ms single half-sine-wave	I_{FSM}	100		A
Maximum instantaneous forward voltage at 3A (Note 1)	V_F	0.5	0.7	V
Maximum DC reverse current $T_A=25^\circ\text{C}$ at rated DC blocking voltage $T_A=100^\circ\text{C}$ (Note 1)	I_R	0.5 20		mA
Typical thermal resistance (Note 2)	$R_{\theta JA}$ $R_{\theta JL}$	50 10		$^\circ\text{C/W}$
Operating junction and storage temperature range	T_J, T_{STG}	-65 to +125		$^\circ\text{C}$

Notes:

- (1) Pulse test: 300 μs pulse width, 1% duty cycle.
- (2) PCB mounted with 0.55" \times 0.55" (14 \times 14mm²) copper pad areas.

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FIG.1 – FORWARD DERATING CURVE

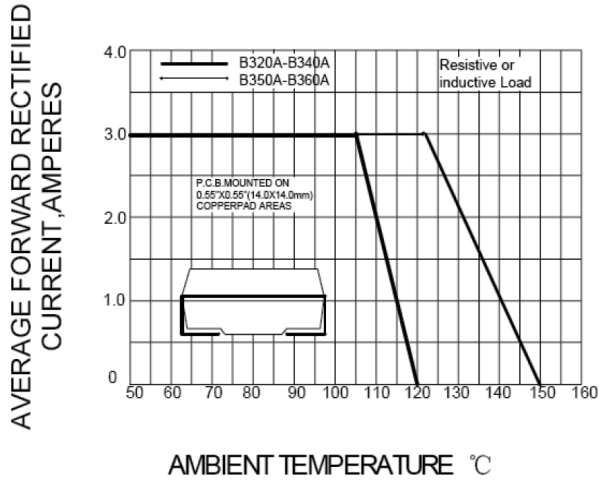


FIG.2- PEAK FORWARD SURGE CURRENT

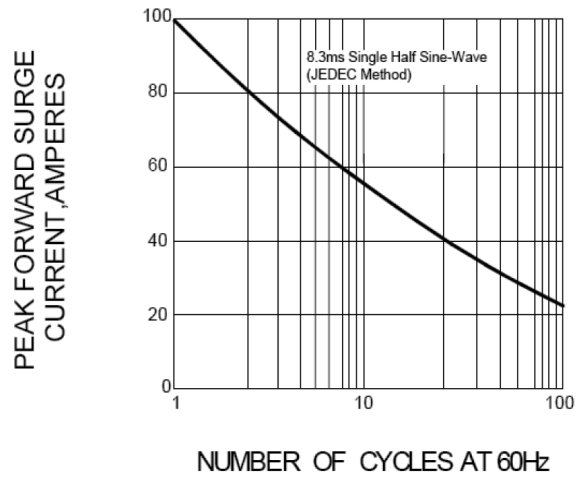


FIG.3 – TYPICAL FORWARD CHARACTERISTICS

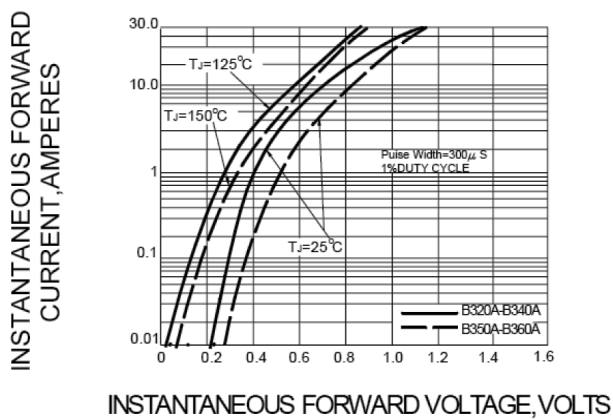
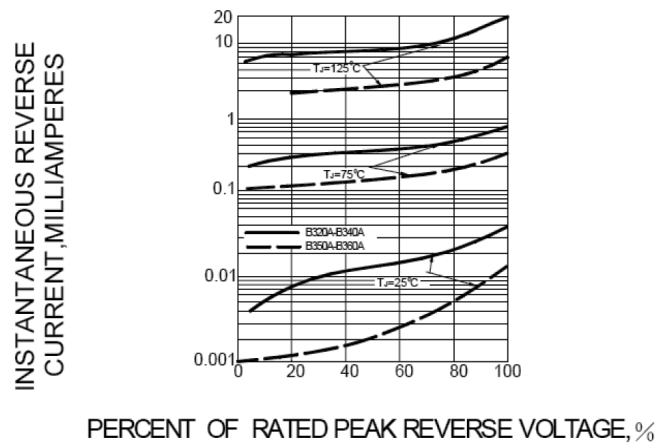


FIG.4 – TYPICAL REVERSE CHARACTERISTICS



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FIG.5-TYPICAL JUNCTION CAPACITANCE

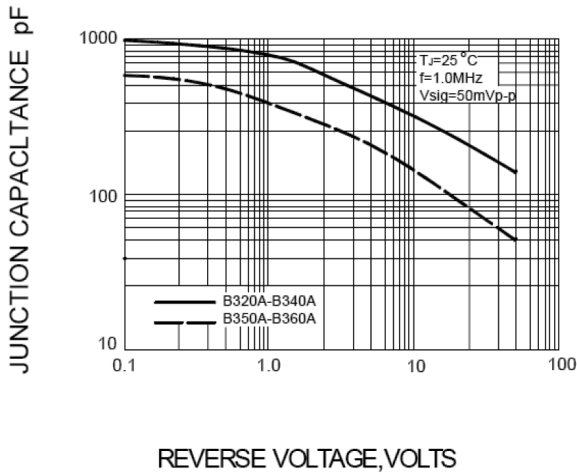
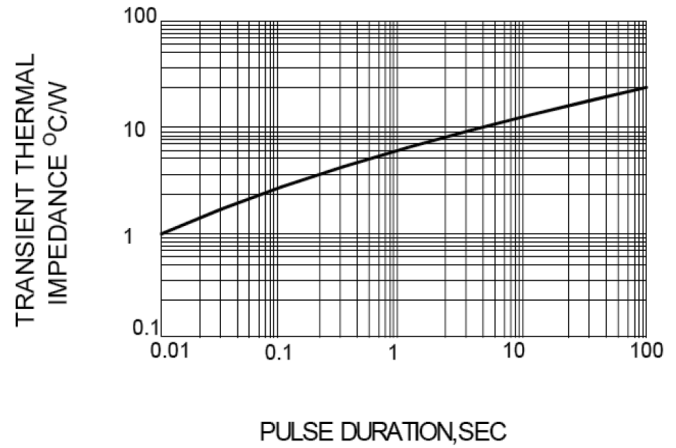
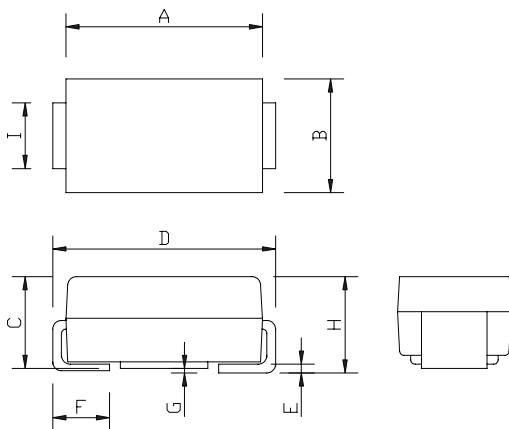


FIG.6- TYPICAL TRANSIENT THERMAL IMPEDANCE



Package Outline Dimensions

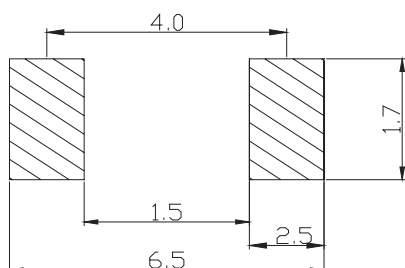


DO-214AC(SMA)		
Dim.	Min.	Max.
A	4.25	4.65
B	2.4	2.8
C	1.85	2.15
D	4.85	5.35
E	0.1	0.3
F	0.9	1.5
G	0.2 Max.	
H	1.9	2.3
I	1.35	1.65

Dimensions : Millimetres

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Soldering Footprint



Dimensions : Millimetres

Package Information

Device	Package	Shipping
B340A-13-F & B360A-13-F	DO-214AC(SMA)	5,000 / Tape & Reel

Part Number Table

Description	Part Number
Schottky Barrier Rectifier	B340A-13-F
	B360A-13-F

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